

#4/Pre-Amdt A/  
Sub Spec (N.G.)  
10/25/81  
D King

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Charles W.C. Lin  
Title: BUMPLESS FLIP CHIP ASSEMBLY WITH SOLDER VIA  
Serial No.: Unknown Filed: Herewith  
Examiner: Unknown Group Art Unit: Unknown  
Atty. Docket No.: P002-2

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ASSISTANT COMMISSIONER FOR PATENTS  
Washington, D.C. 20231

**PRELIMINARY AMENDMENT**

Dear Sir:

Please amend the application as follows.

**In the Abstract and Specification**

Replace the Abstract and Specification with the enclosed Substitute Specification.

**In the Claims**

Cancel claims 1-14 without prejudice or disclaimer to the subject matter recited therein.

Add the following claims: